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「 _	P/N	HOUSING MATERIAL	COLOR	CONTACT PLATING	METAL SHELL PLATING		REMARK	(-	
	67643-0910	POLYESTER	BLACK	GOLD FLASH	IR REFLOW PROCESS			NON IR	`	
	67643-1910	POLYESTER	WHITE				REFLOW PROC	ESS		
	67643-2910	HIGH TEMPERATURE NYLON	BLACK		MATTE TIN PLATED THICKNESS=100 MIC) AT SOLDER AREA ROINCH MINIMUM		FOR IR		
	67643-3910	HIGH TEMPERATURE NYLON	WHITE			UNDER PLATE:NICKEL (Ni),(SOLDERING AVAILABLE)		REFLOW PROC	ESS	
	67643-0911	POLYESTER	BLACK	GOLD PLATING	NON IR REFLOW PROCESS: MATTE TIN PLATED. THICKNESS=80 MICROINCH MINIMUM UNDER PLATE:NICKEL (Ni).		NON IR		D	
D .	67643-1911	POLYESTER	WHITE	30 MICROINCH			REFLOW PROC	ESS		
	67643-2911	HIGH TEMPERATURE NYLON	BLACK					FOR IR		
	67643-3911	HIGH TEMPERATURE NYLON	WHITE				REFLOW PROC	ESS		
<u> </u>	PCB THICKNES	SS	1.60±0.0	5						
	DIMENSION "A"		2.60							c
	P/N	HOUSING MATERIAL	COLOR	CONTACT PLATING	METAL SHELL PLATING FOR IR REFLOW PROCESS MATTE TIN PLATED AT SOLDER AREA THICKNESS-100 MICROINCH MINIMUM		REMARK		_	
	67643-0930	HIGH TEMPERATURE NYLON	BLACK	GOLD FLASH			FOR IR			
	67643-1930	HIGH TEMPERATURE NYLON	WHITE					REFLOW PROCESS		
- L	67643-0931	HIGH TEMPERATURE NYLON	BLACK	GOLD PLATING						
	67643-1931 HIGH TEMPERATURE NYLON		WHITE	30 MICROINCH	UNDER PLATE:NICKEL (Ni),(SOLDERING AVAILABLE)					
LF	PCB THICKNESS		1.20±0.05							
в 📗 🖺	DIMENSION "A"		2.00							В
		Γ	8/28	1 1 4 4 7 7 7 7	RAL TOLERANCES	DIMENSION STYLE		SIGN UNITS	THIRD ANGLE	Ē
A			TE VISED EC NO: ORWN:YPWU 2009/08/28 CHYC:	SYMBOLS (UNLESSYMBOLS) 4 PLACE 3 PLACE 1 PLACE 1 PLACE A DRAFT	SS SPECIFIED) mm		TITLE USB ARA THE STATE OF THE	A TYPE RCI HROUGH HOI AD-FREE V LEX INCOR	PROJECTION PT SINGLE LE W/OFLG /ERSION) PORATED SHEET NO 2 OF 2 PRIETARY TO MOLEX	A A
	2006/04/15	6		5	4	3	2		1	